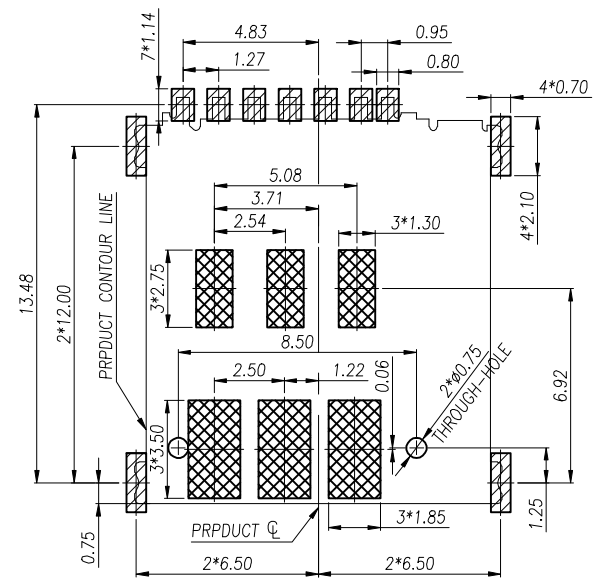
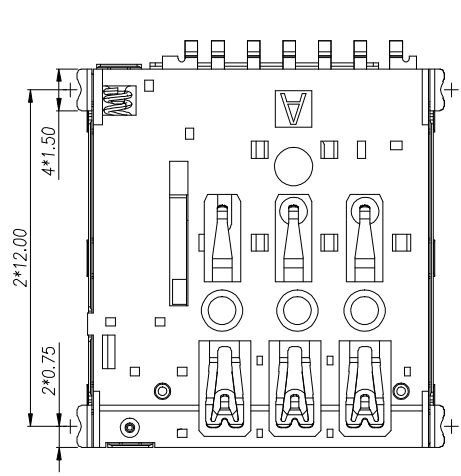
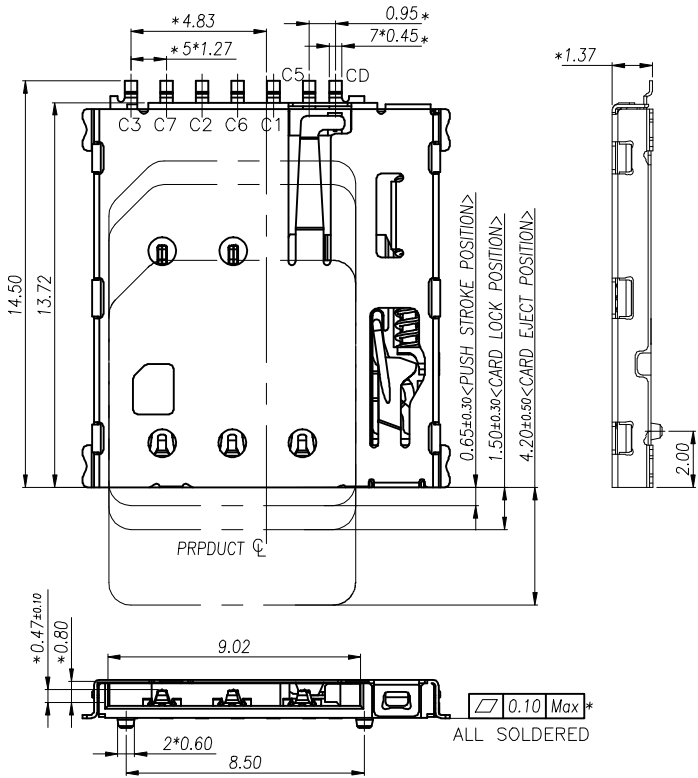


PRELIMINARY  
DESIGN IS SUBJECT  
TO CHANGE WITHOUT  
PRIOR NOTICE

REV.	Q'TY	ECN. NO.	APR.	DATE
A		FIRST RELEASE		

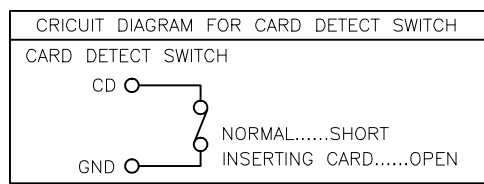


RECOMMENDED PCB LAYOUT TOP VIEW (TOLERANCE:±0.05)  
RECOMMENDED MATAL MASK T=0.12mm

- SMT SOLDER AREA
- NO PATTERN AND VIA HOLE IN HTIS AREA

NOTES:  
1.MATERIAL:  
HOUSING: High Temperature Thermoplastic  
Terminal:Copper Alloy  
Shell: Stainless Steel  
2.PLATING:  
Terminal:50u" Ni UNDERPLATED OVERALL  
G/F PLATED ON CONTACT AREA AND SOLDER AREA  
Shell:30u" Ni UNDERPLATED OVERALL  
G/F PLATED ON CONTACT AREA AND SOLDER AREA  
3.TECHNICAL SPECIALITY:  
RATED VOLTAGE: 30V AC MAX.  
CURRENT RATING: 0.5A MAX.  
INSULATION RESISTANCE:1000MΩ MIN  
CONTACT REISTANCE:50mΩ MAX  
WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTES  
OPERATING TEMPERATURE:  
-25℃~+85℃ Humidity 80% R.H MAX  
4.DIMENSIONS WITH MARK \* MUST BE MEASURE  
BY QC AND IQC

PIIN/NO	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
CD	Detect Switch
C5	GND
C6	VPP
C7	I/O



DIMENSION IN mm		TOLERANCE UNLESS OTHERWISE SPECIFIED		APR.		TITLE: 自弹式 NanoSIM卡卡座	
.X±0.35	X:± 5'			CHK.		DWG NO. BX-SMN-1.37HJ	
.XX±0.25	.X'± 3'			DRA.		PROV.	
.XXX±0.15	.XX'± 1'			SIZE A4		SCALE 4:1 SHEET 1/2 REV. A	

